SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Multilayer Chip Bead	ABC'S DWG NO.	MU1005□□□□L□-□□□		
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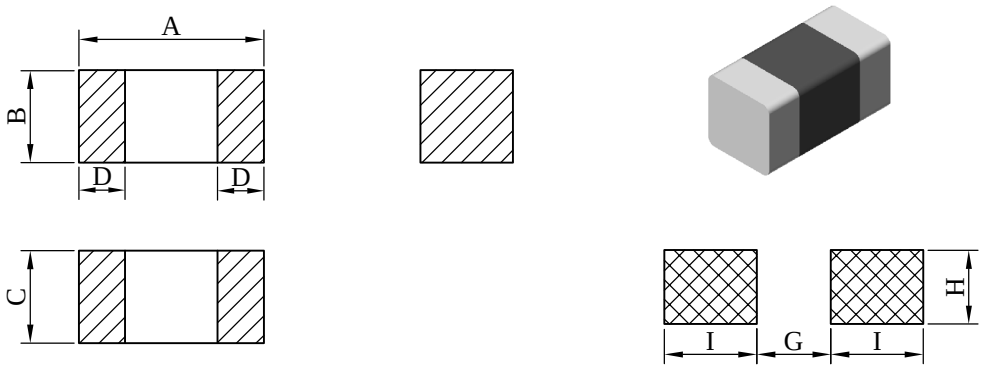
Ⅰ．Configuration and dimensions：



(PCB Pattern)

Unit：m/m

A	B	C	D	G	H	I
1.00 ±0.10	0.50 ±0.10	0.50 ±0.10	0.20 ±0.10	0.40	0.40	0.50

Ⅱ．Materials：

a．Body：Ferrite
b．Internal conductor：Silver
c．Terminal electrode：Ag / Ni / Sn
d．Product weight：1.3 mg（ref.）
e．Products comply with RoHS' requirements
f．Halogen free available.

Ⅲ．General specification：

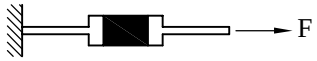
a．Storage Conditions：

Electrical Performance temp：-55℃ ---- +125℃

Terminal Solderability & Packages Material temp：-10℃ ---- +40℃ and RH 70% max.

b．Operating temp.：-55℃ ---- +125℃

c．Terminal strength：



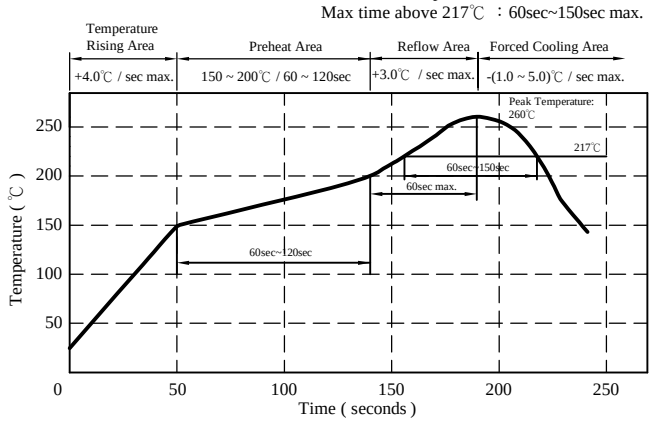
Type	F (kgf)	Time (sec)
MU1005	0.3	30±5

d．Resistance to soldering heat：

Solder temp. : 260℃

Dip time :10 sec max.

Peak Temp：260℃ max.
Max. Peak Temp - 5℃：30sec max.
Max time above 217℃ ：60sec~150sec max.



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Ⅳ . Electrical characteristics：

DWG No.	Impedance (Ω) At 100MHz	DC Resistance (Ω) max	Rated Current (mA) max
MU1005300YL□-□□□	30.0±25 %	0.30	500
MU1005600YL□-□□□	60.0±25 %	0.40	200
MU1005121YL□-□□□	120.0±25 %	0.50	200
MU1005221YL□-□□□	220.0±25 %	0.70	100
MU1005301YL□-□□□	300.0±25 %	0.80	100
MU1005601YL□-□□□	600.0±25 %	1.00	100

1). □：Packaging information：□ Code

2). "-□□□"：Reference code

3). Electrical specifications at 25℃

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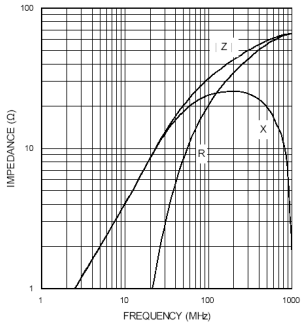
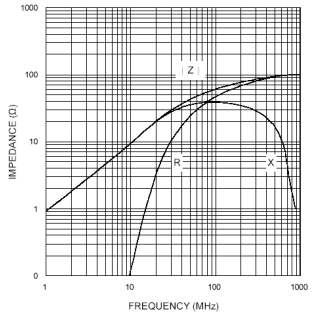
Ⅴ．Impedance VS. Frequency Response Curve：

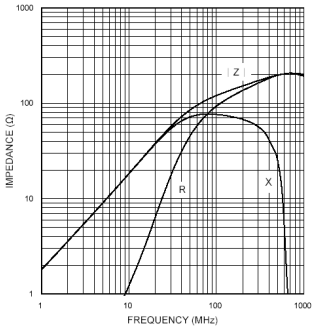
MU1005300Y



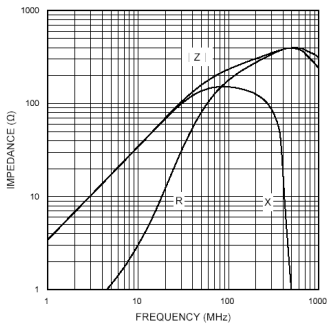
MU1005600Y



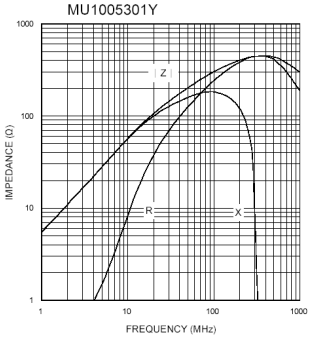
MU1005121Y



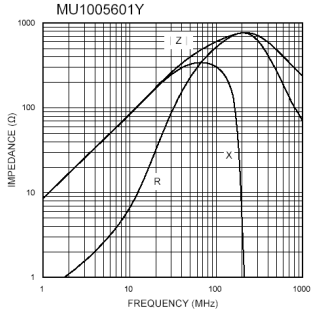
MU1005221Y



MU1005301Y



MU1005601Y



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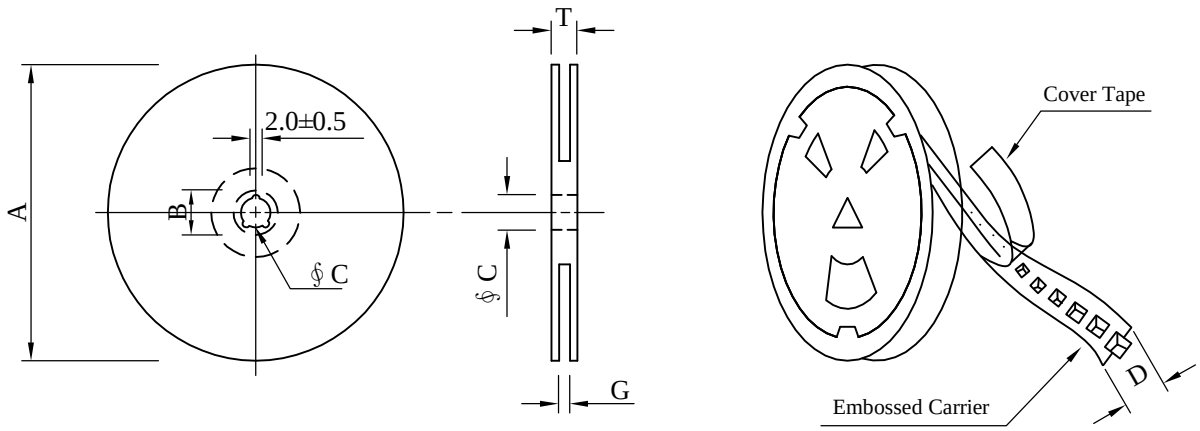
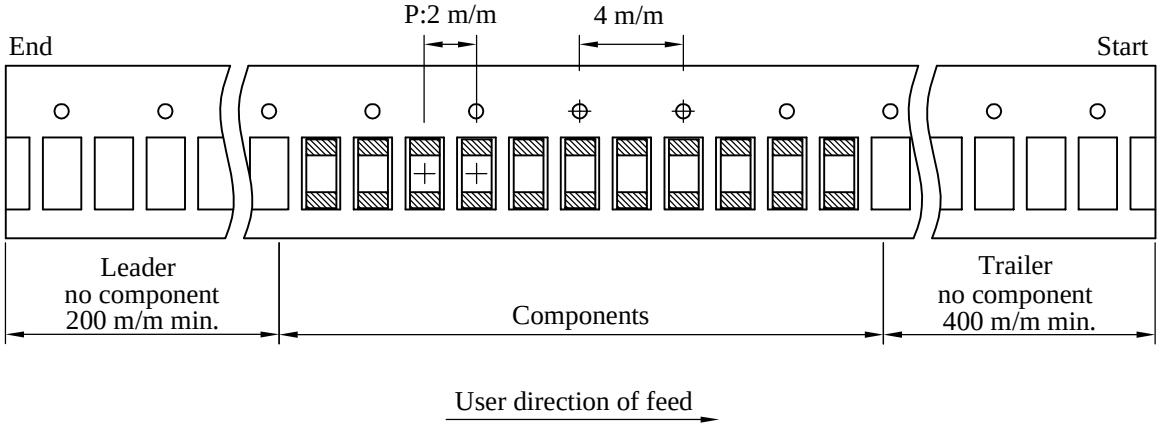
Ⅵ． Packaging information：

(1) Configuration



※Carrier tape width : D



(2) Dimensions Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10^{+0}	50^{-0}	12.5

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY(kpcs)	G.W. (Kg)	Size (cm)
B	10,000	60	07 - 08	500	5.5	42 x 41 x 24

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Ⅶ．Reliability test：

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125℃ 2.Time:1008 hours. 3.Measurement：After placing for 24 hours min.	1.Body: No damage 2.Impedance shall not change more than ±30%.
2.Low Temperature Exposure	JESD22-A119	1.Temperature: -55℃ 2.Time:1008 hours. 3.Measurement：After placing for 24 hours min.	1.Body: No damage 2.Impedance shall not change more than ±30%.
3.Temperature Cycling	JESD22-A 104	1.Temperature: -55℃ ~ 125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes 4.Measurement：After placing for 24 hours min.	1.Body: No damage 2.Impedance shall not change more than ±30%.
4.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature:40±5 ℃ 2.Time:1008 Hours 3.Humidity: 95% RH. 4.Measurement：After placing for 24 hours min.	1.Body: No damage 2.Impedance shall not change more than ±30%.
5.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-55-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	Appearance: No damage
6.Resistance To Soldering Heat Test	MIL-STD-202 Method 210	1.Solder Temp. : 265±3℃ 2.Immersion time : 6±1 sec 3.Preheating : 100℃ to 150℃, 1 minute. 4.Measurement：After placing for 24 hours min.	1.Appearance: No damage 2.Impedance shall not change more than ±30%.
7.Solderability Test	J-STD-002	1.Preheat：150℃,60 seconds 2.Solder temperature：245±5℃ 3.Flux 4.Dip time：4±1 seconds	The terminal shall be at least 90% covered with fresh solder.
8.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force: Refer to product specification. 3.Dwell time : >25 seconds.	The terminal electrode and the body shall not be damaged by the forces applied on the right conditions.
9.Board Flex	JIS-C-6429	1.Deflection speed：1 mm/ sec 2.Amount of deflection：2 mm 3.Span：90 mm 4.Direction for test：Bottom of PCB 5.Holding time : 60 seconds.	1.Appearance: No damage 2.The terminal electrode and the body shall not be damaged by the forces applied on the right conditions.